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Patent

FEB 13 2006

Customer No.: 31561
Docket No.: 10544-US-PA
Application No.: 10/709,179

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicants : Chang et al.
Application No. : 10/709,179
Filed : April 19, 2004
For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD
OF FABRICATING BUMPS ON THE BACKSIDE OF A
CHIP
Art Unit : 2814
Examiner : HA, NATHAN W.

TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 1+2 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314

In response to the Advisory Action dated January 30, 2006, please find a *Notice of Appeal* in 2 pages.

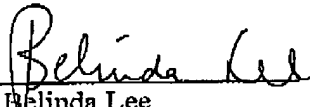
Please charge the payment in the amount of USD \$500.00 for filing the Notice of Appeal and of USD \$120.00 for one-month extension fee to account No. 50-2620 (Order No.: 10544-US-PA).

If the payment is not fully covered in response thereof, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No.: 50-2620 (Order No.: 10544-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: February 13, 2006

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